TECHNICAL SPECIFICATION	ENAVISION 400-TWIN-P
OVERVIEW	
Build Envelop Volume (mm³)	400X400X300 (9,8x9,8x11,8 in)
Range of Layer Thickness	20-100 µm (0,0007 - 0,004 in)
Feature Thickness	150 µm
Laser Type	Fiber laser
Laser Power	500 W (Single Mode) **x 2**
Scanning Speed	Up to 11 m/S (433,07 in)
Scanning System	3D dynamic focused scanning system **x 2**
Dimension (LxWxH)	3200 x1500x2030 (125,98x64,57x79,9 in)
Electrical Connection (Voltage)	480 V, 3 PH, 60 Hz
Electrical Connection (Current)	40 A
Inert Gas	Argon / Nitrogen
O2 Level	<100 ppm
Vacuum Pump	Yes
Operating System	Windows 10 / X
Network	Ethernet / Ethercat
Build Plate Temperature	0- 200 °C
OPTICAL SCANNING SYSTEM	
Scanning Speed	Up to 11 m/S (433,07 in)
Scannıng System	3D dynamic focused scanning system **x 2**
Cooling System	Water
CONTROL UNIT	
Ccontrol System	Beckhoff Industrial PC
Processor	Intel i5-i7
Operating System	Windows 10 / X
HMI	21.5 in, touch operated
SOFTWARE	
Data Preparation Software	Materiliase Magics and Modules
Data Processing Software	Ermaksan Build Processor
Supported File Types	STL , 3MF, AMF,, DAE , FBX, VRML …
FEATURES	
Beam Focus Diameter/Beam Diameter	100 µm
Beam Correction	Auto
Recoater blade	Silicon
Dimensional accuracy	± 100 µm
Surface roughness	Ra<20µm
Relative Density of as printed parts	≥99%
Process Monitoring Camera	HD Camera to follow the building process
Quality Comformation	CE